



AF

AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 2827  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q66510

Toshio SHINTANI, et al.

Appln. No.: 09/974,048

Group Art Unit: 2827

Confirmation No.: 7616

Examiner: Tuan T. DINH

Filed: October 11, 2001

For: CIRCUIT BOARD AND CONNECTION STRUCTURE OF TERMINAL PORTION OF  
THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.116

ATTN: BOX AF  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated December 20, 2002, please amend the above-identified application as follows:

**IN THE CLAIMS:**

1. (Currently Amended) A circuit board comprising:  
a terminal portion connected with an external terminal formed in an external circuit, said terminal portion provided with a nickel plating layer and a soldering bump;  
wherein a thickness of said nickel plating layer is within a range of 1.0 to 4.0  $\mu\text{m}$ ,

RECEIVED  
MAR 25 2003  
10 2800 MAIL ROOM